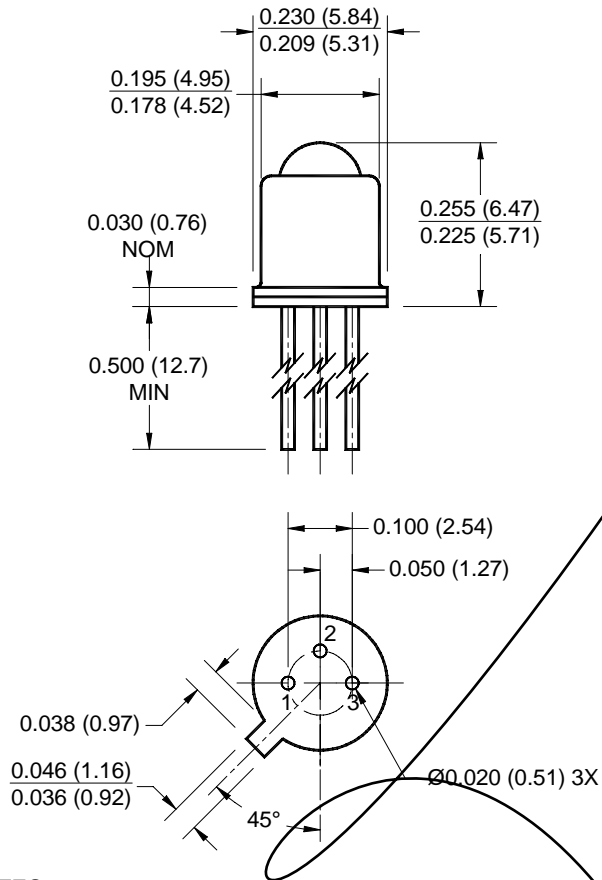




PACKAGE DIMENSIONS



NOTES:

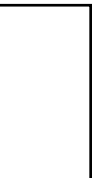
1. Dimensions for all drawings are in inches (mm).
2. Tolerance of $\pm .010$ (.25) on all non-nominal dimensions unless otherwise specified.

DESCRIPTION

The L14F1/L14F2 are silicon photodarlington mounted in a narrow angle, TO-18 package.

FEATURES

- Hermetically sealed package
- Narrow reception angle



L14F1 L14F2

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Rating | Unit |
|---|-------------|----------------|------------------|
| Operating Temperature | T_{OPR} | -65 to +125 | $^\circ\text{C}$ |
| Storage Temperature | T_{STG} | -65 to +150 | $^\circ\text{C}$ |
| Soldering Temperature (Iron) ^(3,4,5 and 6) | T_{SOL-I} | 240 for 5 sec | $^\circ\text{C}$ |
| Soldering Temperature (Flow) ^(3,4 and 6) | T_{SOL-F} | 260 for 10 sec | $^\circ\text{C}$ |
| Collector to Emitter Breakdown Voltage | V_{CEO} | 25 | V |
| Collector to Base Breakdown Voltage | V_{CBO} | 25 | V |
| Emitter to Base Breakdown Voltage | V_{EBO} | 12 | V |
| Power Dissipation ($T_A = 25^\circ\text{C}$) ⁽¹⁾ | P_D | 300 | mW |
| Power Dissipation ($T_C = 25^\circ\text{C}$) ⁽²⁾ | P_D | 600 | mW |

NOTE:

1. Derate power dissipation linearly 3.00 mW/ $^\circ\text{C}$ above 25 $^\circ\text{C}$ ambient.
2. Derate power dissipation linearly 6.00 mW/ $^\circ\text{C}$ above 25 $^\circ\text{C}$ case.
3. RMA flux is recommended.
4. Methanol or isopropyl alcohols are recommended as cleaning agents.
5. Soldering iron tip 1/16" (1.6mm) minimum from housing.
6. As long as leads are not under any stress or spring tension.
7. Light source is a GaAs LED emitting light at a peak wavelength of 940 nm.
8. Figure 1 and figure 2 use light source of tungsten lamp at 2870 $^\circ\text{K}$ color temperature. A GaAs source of 0.05 mW/cm² is approximately equivalent to a tungsten source, at 2870 $^\circ\text{K}$, of 0.2 mW/cm².

ELECTRICAL / OPTICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$) (All measurements made under pulse conditions)

| PARAMETER | TEST CONDITIONS | SYMBOL | MIN | TYP | MAX | UNITS |
|------------------------------------|---|-------------|-----|---------|-----|---------------|
| Collector-Emitter Breakdown | $I_C = 10 \text{ mA}, E_e = 0$ | BV_{CEO} | 25 | | — | V |
| Emitter-Base Breakdown | $I_E = 100 \mu\text{A}, E_e = 0$ | BV_{EBO} | 12 | | — | V |
| Collector-Base Breakdown | $I_C = 100 \mu\text{A}, E_e = 0$ | BV_{CBO} | 25 | | — | V |
| Collector-Emitter Leakage | $V_{CE} = 12 \text{ V}, E_e = 0$ | I_{CEO} | — | | 100 | nA |
| Reception Angle at 1/2 Sensitivity | | θ | | ± 8 | | Degrees |
| On-State Collector Current L14F1 | $E_e = .125 \text{ mW/cm}^2, V_{CE} = 5 \text{ V}^{(7)}$ | $I_{C(ON)}$ | 7.5 | | — | mA |
| On-State Collector Current L14F2 | $E_e = .125 \text{ mW/cm}^2, V_{CE} = 5 \text{ V}^{(7)}$ | $I_{C(ON)}$ | 2.5 | | | mA |
| Rise Time | $I_C = 10 \text{ mA}, V_{CC} = 5 \text{ V}, R_L = 100 \Omega$ | t_r | | 300 | | μs |
| Fall Time | $I_C = 10 \text{ mA}, V_{CC} = 5 \text{ V}, R_L = 100 \Omega$ | t_f | | 250 | | μs |

L14F1 L14F2

Figure 1. Light Current vs. Collector to Emitter Voltage

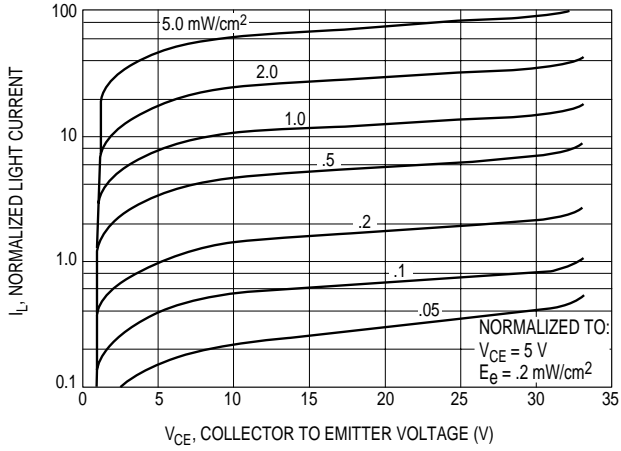


Figure 2. Relative Light Current vs. Ambient Temperature

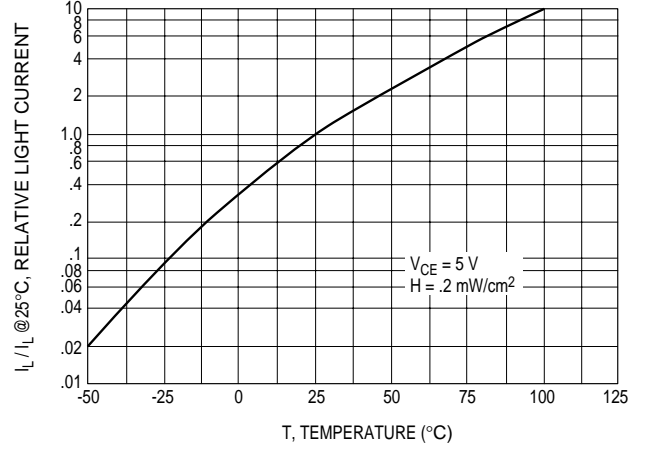


Figure 3. Spectral Response

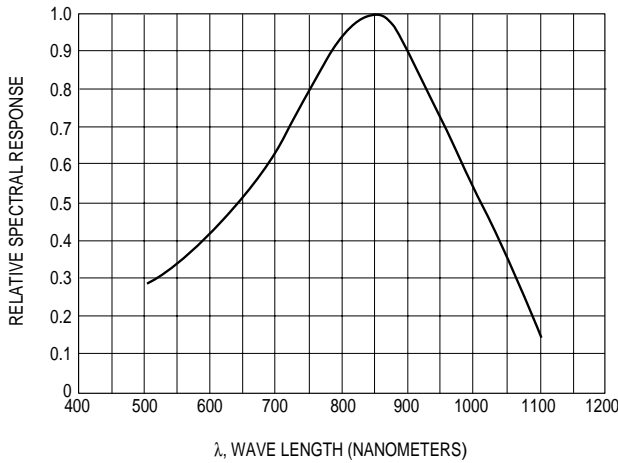


Figure 4. Angular Response

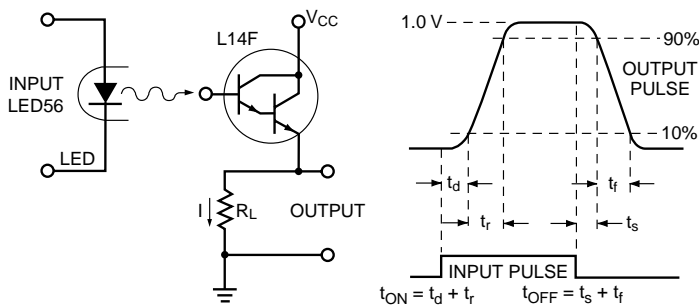
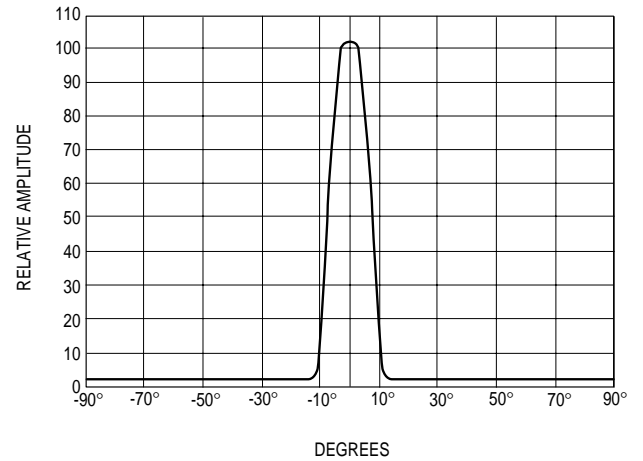
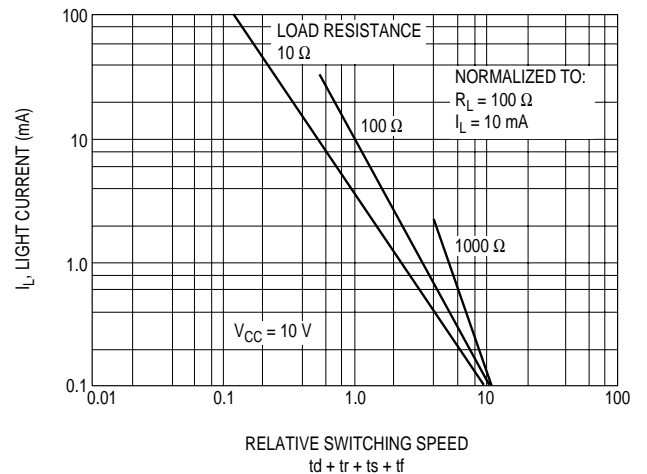


Figure 5. Test Circuit and Voltage Waveforms

Figure 6. Light Current vs. Relative Switching Speed



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